P-Channel 30-V (D-S) MOSFET With Schottky Diode

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low $r_{DS(on)}$ and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

- Low r_{DS(on)} provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe TSOP-6 saves board space
- Fast switching speed
- High performance trench technology

MOSFET PRODUCT SUMMARY							
V _{DS} (V)	r _{DS(on)} (OHM)	I _D (A)					
-26.5	$0.130 @ V_{GS} = -4.5V$	±2.5					
-20.3	$0.190 @ V_{GS} = -2.5V$	±1.9					

SCHOTTKY PRODUCT SUMMARY

V _{KA} (V)	V _f (V) Diode Forward Voltage	I _F (A)		
30	0.48V @ 1.0A	1.0		
	TSOP-6			

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ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C UNLESS OTHERWISE NOTED)									
Parameter						Maximum	Units		
Drain-Source Voltage (MOSFET)					V _{DS}	-26.5			
Reverse Voltage (Schottky)					V _{KA}	30	V		
Gate-Source Voltage (MOSFET)					V _{GS}	±12			
		$T_A=2$		ID	±2.5				
Continuous Drain Current (1) 150 C	.) (MOSELT)		$T_A = 7$	$70^{\circ}C$	чр	±1.9	А		
Pulsed Drain Current (MOSFET) ^b					I _{DM}	±10			
Continuous Source Current (MOSFE	ET Diode Conduc	tion) ^a	L		Is	-1.6			
Average Forward Current (Schottky)					$I_{\rm F}$	0.5			
Pulsed Forward Current (Schottky)					I_{FM}	8			
Maximum Power Dissipation (MOS	EET) ^a		$T_A=2$	25°C		1.15			
	(°E1)		$T_A = 7$	$70^{\circ}C$	D_	0.7	W		
			$T_A=2$	25°C	P _D	1.0	W		
Maximum Fower Dissipation (Schot	Maximum Power Dissipation (Schottky) ^a $T_A=70^{\circ}C$			$70^{\circ}C$		0.6			
Operating Junction and Storage Temperature Range					T _J , T _{stg}	-55 to 150	°C		
THERMAL RESISTANCE RATI	NGS								
Parameter		Syn	nbol	7	Гур	Max			
Maximum Junction-to-Ambient ^a	t <= 10 sec	R _{thJA}			93	110	°C/W		
Maximum Junction-to-Ambient	Steady State				130	150	C/ W		

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

b. Pulse width limited by maximum junction temperature

AM3837P

MOSFET SPECIFICATIONS ($T_A = 25^{\circ}C$ UNLESS OTHERWISE NOTED)									
Parameter	Symbol	Test Conditions		1.1					
Farameter	Symbol	Test Conditions	Min	Тур	Max	Unit			
Static									
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \text{ uA}$	-1.0						
Gate-Body Leakage	I _{GSS}	V_{DS} = 0 V, V_{GS} = +/-12 V			±100	nA			
Zero Gate Voltage Drain Current		V_{DS} = -21 V, V_{GS} = 0 V			-1	uA			
	I _{DSS}	V_{DS} = -21 V, V_{GS} = 0 V, T_{J} = 55°C			-10				
On-State Drain Current ^A	I _{D(on)}	V_{DS} = -5 V, V_{GS} = -4.5 V	-5			Α			
Davis October Desister of	r	V _{GS} = -4.5 V, I _D = -2.5 A			0.130	Ω			
Drain-Source On-State Resistance ^A	r _{DS(on)}	V_{GS} = -2.5 V, I _D = -1.9 A			0.190	Ω			
Forward Tranconductance ^A	g _{fs}	V _{DS} = -5 V, I _D = -2.5 A		3		S			
Diode Forward Voltage	V_{SD}	I _S = -1.6 A, V _{GS} = 0 V		-0.70		V			
Dynamic ^b									
Total Gate Charge	Qg			6.0					
Gate-Source Charge	Q _{gs}	V _{DS} = -5 V, V _{GS} = -4.5 V, I _D = -2.5 A		0.80		nC			
Gate-Drain Charge	Q _{gd}	$I_{\rm D} = -2.3$ R		1.30					
Turn-On Delay Time	t _{d(on)}			6.5					
Rise Time	tr	$V_{DD} = -5 V, R_{L} = 5 OHM,$		20		1			
Turn-Off Delay Time	t _{d(off)}	V_{GEN} = -4.5 V, R_G = 6 OHM		31		ns			
Fall-Time	t _f			21		1			

SCHOTTKY SPECIFICATIONS ($T_A = 25^{\circ}C$ UNLESS OTHERWISE NOTED)								
Parameter	Symphol	Test Conditions		1.1				
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit		
	V _F	I _F = 0.5 A			0.48	V		
Forward Voltage Drop	۷F	I _F = 0.5 A, Τ _J = 125 [°] C			0.4	V		
		$V_r = 30 V$			0.1	mA		
Maximum Reverse Leakage Current	I _{rm}	$V_r = 30 V, T_J = 75^{\circ}C$			1			
		$V_r = 30 V, T_J = 125^{\circ}C$			10			
Junction Capacitance	CT	V _r = 10 V		31		pF		

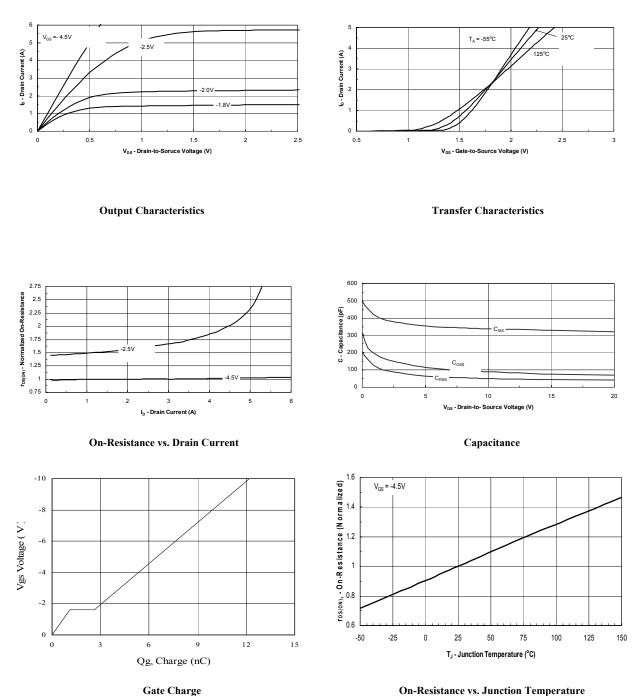
Notes

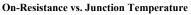
a. Pulse test: $PW \le 300$ us duty cycle $\le 2\%$.

b. Guaranteed by design, not subject to production testing.

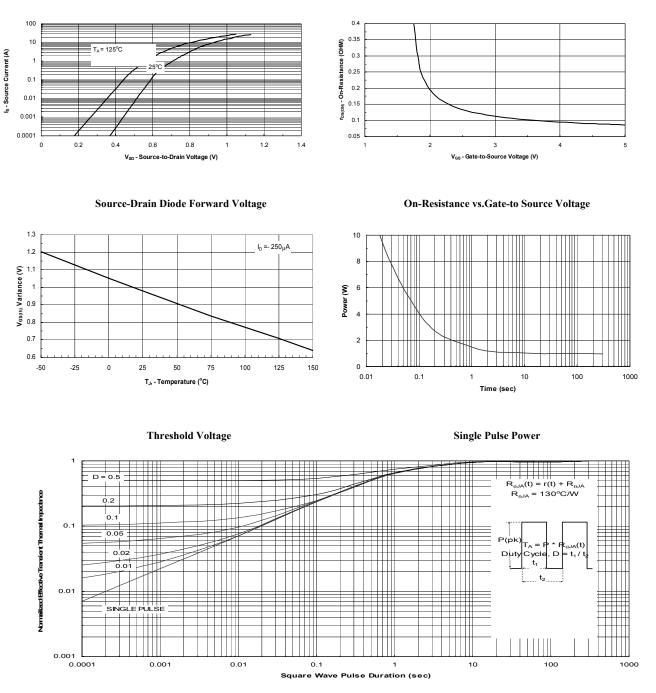
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Typical Electrical Characteristics





Typical Electrical Characteristics



Normalized Thermal Transient Impedance, Junction-to-Ambient

